

SN54AS756, SN74AS756, SN74AS757 OCTAL BUFFERS AND LINE DRIVERS WITH OPEN-COLLECTOR OUTPUTS

SDAS040B – DECEMBER 1983 – REVISED JANUARY 1995

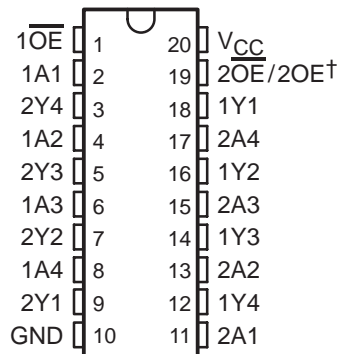
- Open-Collector Outputs Drive Bus Lines or Buffer Memory Address Registers
- Eliminate the Need for 3-State Overlap Protection
- pnp Inputs Reduce dc Loading
- Open-Collector Versions of 'AS240A and 'AS241
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

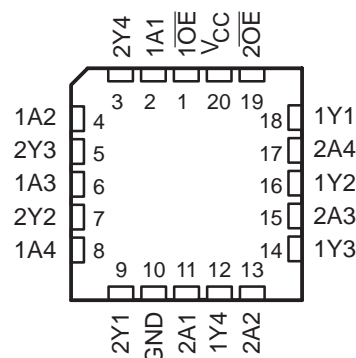
These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters by eliminating the need for 3-state overlap protection. The designer has a choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs. These devices feature high fan-out and improved fan-in.

The SN54AS756 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74AS756 and SN74AS757 are characterized for operation from 0°C to 70°C .

SN54AS756 . . . J PACKAGE
SN74AS756, SN74AS757 . . . DW OR N PACKAGE
(TOP VIEW)

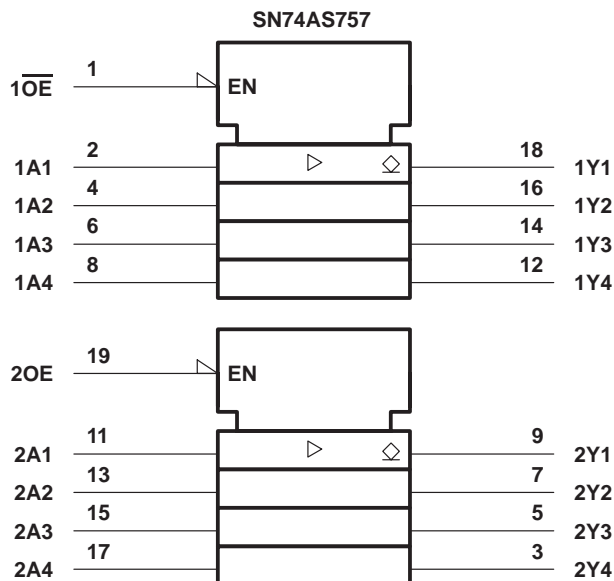
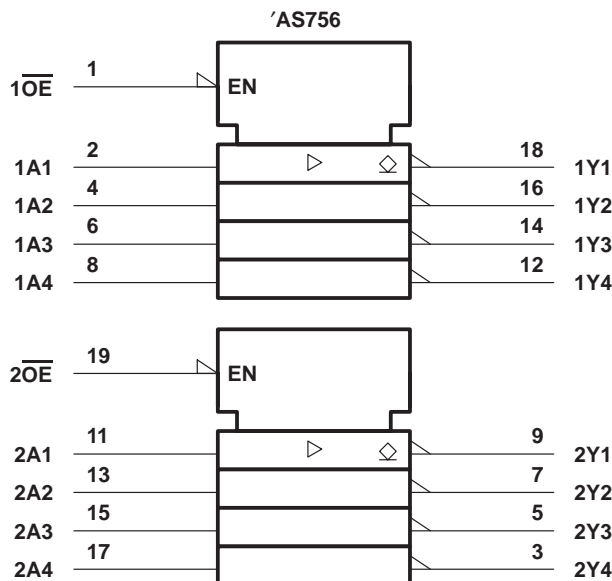


SN54AS756 . . . FK PACKAGE
(TOP VIEW)



$^{\dagger} 2\overline{OE}$ for 'AS756 or $2OE$ for SN74AS757

logic symbols ‡



‡ These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

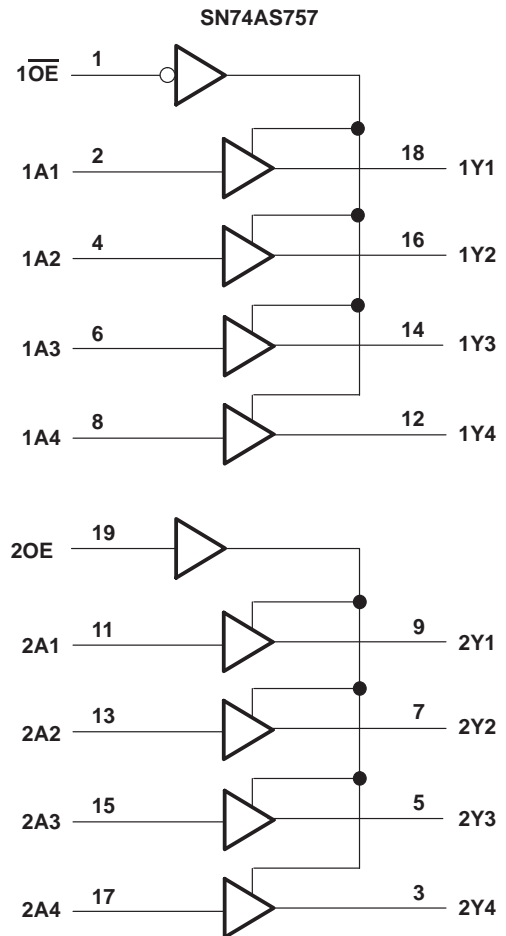
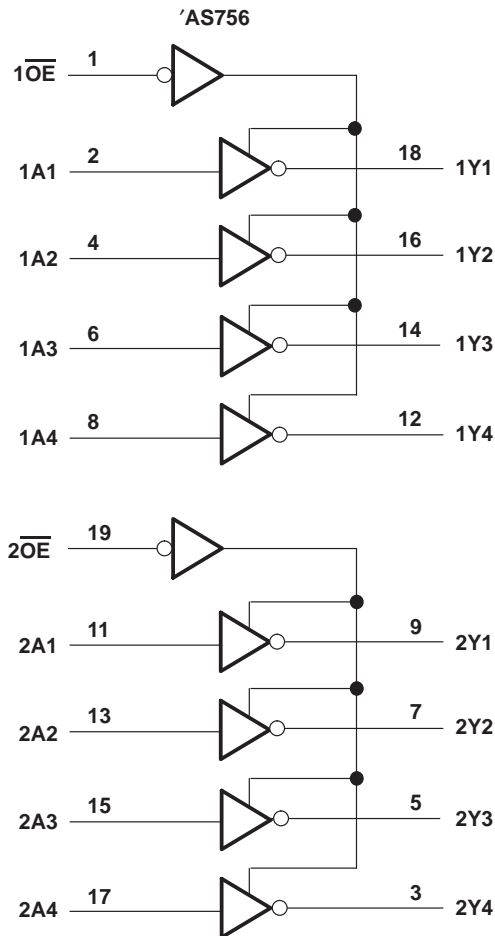


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logic diagrams (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Off-state output voltage	7 V
Operating free-air temperature range, T_A : SN54AS756	-55°C to 125°C
SN74AS756, SN74AS757	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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SDAS040B – DECEMBER 1983 – REVISED JANUARY 1995

recommended operating conditions

		SN54AS756			SN74AS756 SN74AS757			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			48			64	mA
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54AS756		SN74AS756 SN74AS757		UNIT	
				MIN	TYP†	MAX	MIN		TYP†
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2		-1.2	V
I_{OH}		$V_{CC} = 4.5\text{ V}$,	$V_{OH} = 5.5\text{ V}$			0.1		0.1	mA
V_{OL}		$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$			0.55			V
			$I_{OL} = 64\text{ mA}$					0.55	
I_I		$V_{CC} = 5.5\text{ V}$,	$V_I = 7\text{ V}$			0.1		0.1	mA
I_{IH}		$V_{CC} = 5.5\text{ V}$,	$V_I = 2.7\text{ V}$			20		20	μA
I_{IL}	A inputs of SN74AS757 only	$V_{CC} = 5.5\text{ V}$,	$V_I = 0.4\text{ V}$			-1		-1	mA
	All other inputs					-0.5		-0.5	
I_{CC}	'AS756	$V_{CC} = 5.5\text{ V}$	Outputs high	9	15		9	15	mA
			Outputs low	51	80		51	80	
	SN74AS757		Outputs high	21	33		21	33	
			Outputs low	61	95		61	95	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54AS756		SN74AS756		
			MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	3	20	3	19	ns
t _{PHL}			1	7	1	6	
t _{PLH}	\overline{OE}	Y	3	22	3	19.5	ns
t _{PHL}			1	8.5	1	7.5	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

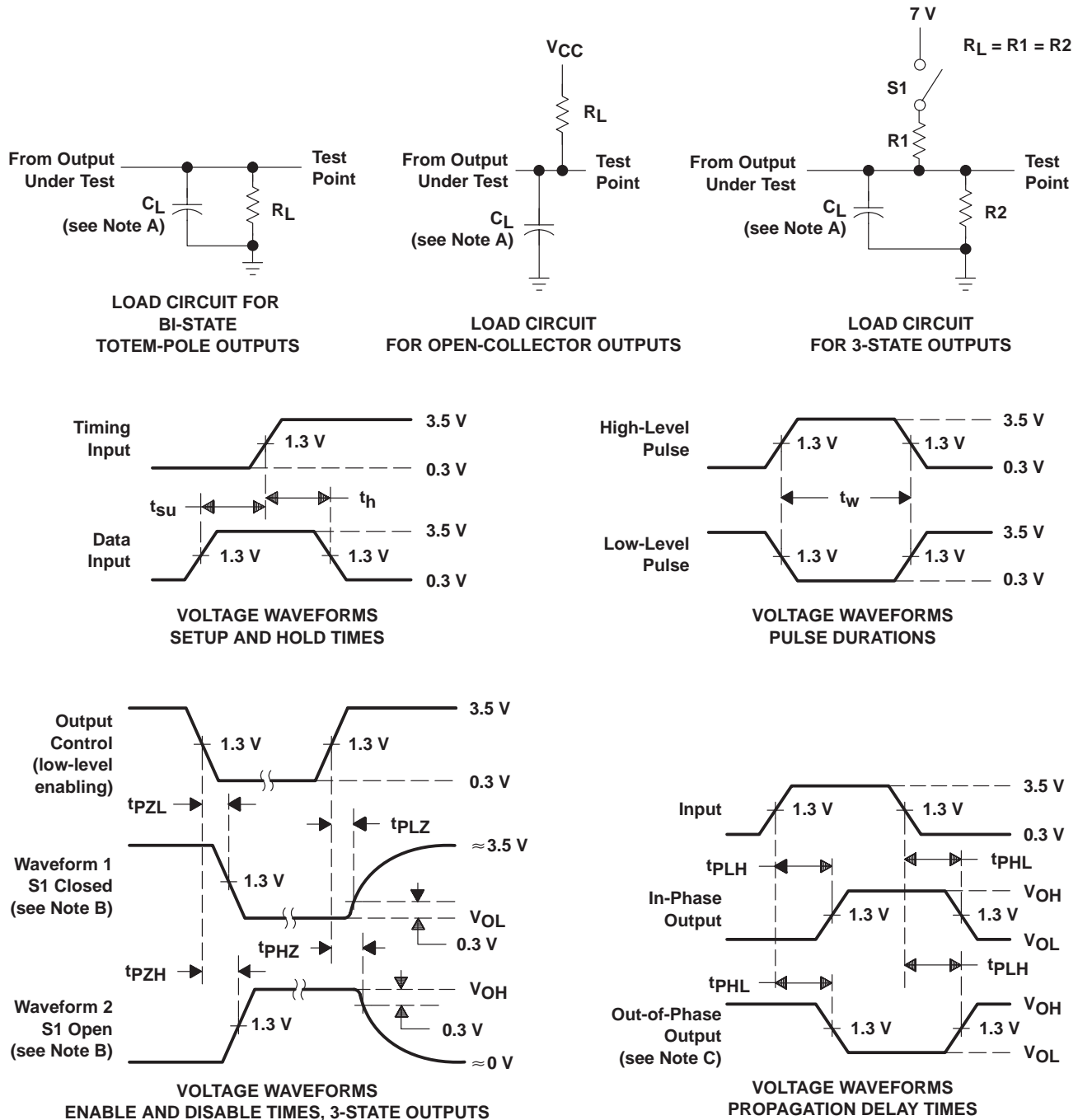
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†		UNIT
			SN74AS757		
			MIN	MAX	
t _{PLH}	A	Y	3	18.5	ns
t _{PHL}			1	6	
t _{PLH}	$\overline{1OE}$	1Y	3	20	ns
t _{PHL}			1	7	
t _{PLH}	2OE	2Y	3	21	ns
t _{PHL}			1	7.5	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



PARAMETER MEASUREMENT INFORMATION
 SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-90563012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9056301RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-9056301SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
SN54AS756J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74AS756DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS756DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS756DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS756DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS756DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS756DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS756N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS756NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS757DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS757DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS757DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS757DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS757DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS757DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS757N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS757NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54AS756FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54AS756J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54AS756W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54AS756, SN74AS756 :

● Catalog: [SN74AS756](#)

● Military: [SN54AS756](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS

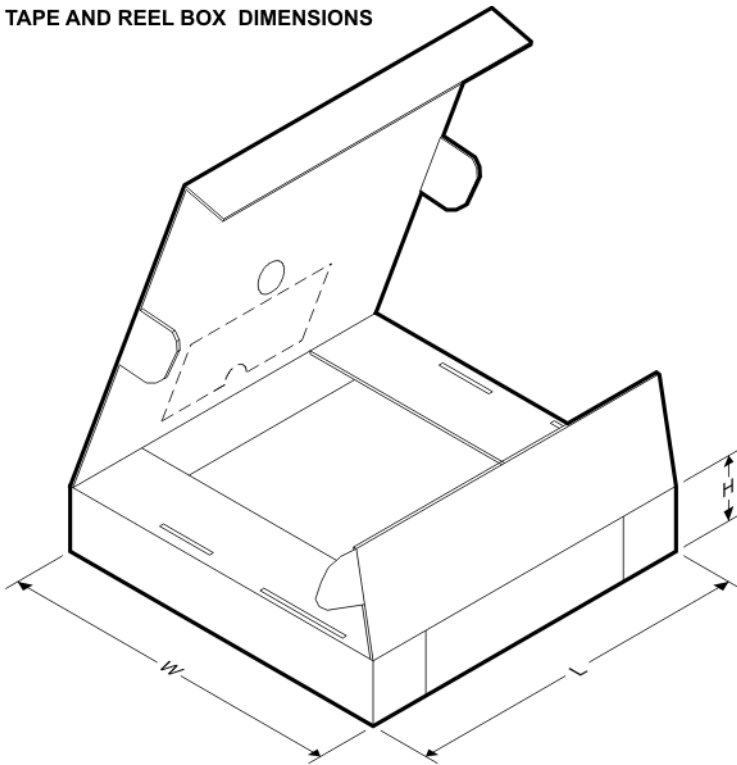

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AS756DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AS757DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AS756DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AS757DWR	SOIC	DW	20	2000	367.0	367.0	45.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

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